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(54) Title: LIQUID COOLING APPARATUS HAVING MULTIPLE FLOW PATHWAYS FOR DIFFERENT ONBOARD HEAT GENERATING ELECTRONIC COMPONENTS

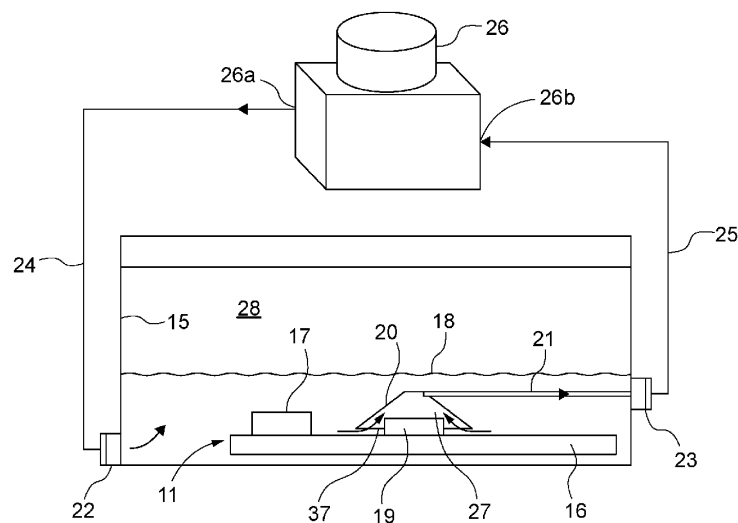


Fig. 3

(57) Abstract: A liquid cooling apparatus and system for the immersion cooling of electronic devices including in particular servers and other IT hardware nodes having an array of heat generating devices including microprocessors, RAM, motherboards etc having different operational temperatures. The present apparatus and system is adapted for at least an in-series flow of cooling liquid in direct contact with the different heat generating devices so as to provide multi-stage heat transfer phases for enhanced energy efficiency and operational control and performance of the electronic device.

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